

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Shigeyuki MARUYAMA, et al.

Serial Number: 09/577,932

Filed: May 25, 2000

For: SEMICONDUCTOR DEVICE HAVING AN
ALIGNMENT MARK FORMED BY THE SAME
MATERIAL WITH A METAL POST

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TECHNICAL SERVICES
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T. Flores

Group Art Unit: 2815

Examiner: C. Chu

Commissioner for Patents
Washington, D.C. 20231

December 5, 2001

Sir:

In response to the Office Action dated September 21, 2001, the following amendments and remarks are respectfully submitted. Reconsideration of the claims is respectfully requested. Please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

The paragraph beginning at page 24, line 18, has been replaced with the following rewritten paragraph:

--The semiconductor device 30 comprises: a semiconductor chip 32 formed on a wafer; a redistribution layer 34 formed on the semiconductor chip 32; a plurality of electrode pads 36 formed on the redistribution layer 34; and a plurality of solder balls 38 as protruding electrodes formed on the electrode pads 36. The redistribution